
PRODUCT CHANGE NOTICE

**Alternate Manufacturing Site
for Assembly of the Listed
Intersil QFN Packaged
Products**

**Refer to:
PCN12006**

Date: January 18, 2012

January 18, 2012

To: Our Valued Intersil Customer

Subject: **Alternate Manufacturing Site for Assembly of the Listed Intersil QFN Packaged Products –STATS ChipPAC (SCM) - Kuala Lumpur, Malaysia**

This notice is to inform you that Intersil is using the STATS ChipPAC (SCM) facility, located in Kuala Lumpur, Malaysia, as an alternate site for performing assembly of the listed QFN (Quad Flat No Lead) packaged products. Products manufactured at the SCM facility will be assembled using copper bond wire as an alternate to the gold bond wire currently used today. The advantages of copper bond wire include improved electrical conductivity of the wire, slower intermetallic growth, reduced wire sweep, and equivalent reliability performance. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. As of this notice, all product and package specific qualification activities are complete.

Products affected:

ISL6262ACRZ

ISL97645AIRZ

ISL97645AIRZ-T

ISL97645AIRZ-TK

The STATS ChipPAC Malaysia (SCM) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and currently qualified as a primary supplier to Intersil for assembly of QFN packaged products with both copper and gold bond wire material. There will be no change in the package outline drawing (POD). Products assembled at SCM with copper bond wire are classified as moisture sensitivity level three (MSL 3 at 260°C per J-STD-020). The qualified material set combinations for the current facilities and SCM are as follows:

Material	Carsem-S (ISL97645A)	Unisem (ISL6262A)	SCM
Mold Compound	Sumitomo EME-G770H	Sumitomo EME-G770HCD	Sumitomo EME-G770
Die Attach	Hysol QMI 519	Ablebond A8290	Ablebond A8290
Bond Wire	1.3 mil Gold (Au)	1.2 mil Gold (Au)	1.2 mil Copper (Cu)

The assembly qualification activity is considered complete as the existing qualified processes, materials, and equipment used to assemble current QFN products at SCM will be used for these products going forward. The reliability summary is included for reference. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at SCM using copper bond wire material may also be identified by the assembly site code (country of assembly) when marked on the devices. The site code for product assembled at SCM with copper bond wire is "M".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product assembled at either the current or the newly qualified sites beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster

Jon Brewster
Intersil Corporation

PCN12006

CC: J. Touvell D. Decrosta D. Foster S. Nadarajah D. Grener J. Murkland J. Wei R. Montero

PCN12006 – Reliability Summary

Stress / Conditions	Duration	ISL9214 3X3 QFN	ISL6236 5X5 QFN	ISL6312 7X7 QFN
HTOL Ta = 125C	1000 Hours	0/78	N/A	0/78
Biased HAST 130C / 85%	96 Hours	0/78	N/A	0/78
High Temp Storage Ta = 150C	1000 Hours	0/78	0/78	0/78
Acc. Bond Integrity (ABI) / Wire Pull Ta = 175C	96 Hours	0/15	0/15	0/15
ubHAST 130C / 85% RH	96 Hours	0/78	0/75	0/78
Temp Cycle IND +125C / -40C	1000 Cycles	0/234	0/234	0/234
Temp Cycle MIL +150C / -65C	500 Cycles	0/234	0/234	0/234